In the claims:

1. (currently amended) A method of dissipating heat in an electrically active interconnect line in an integrated circuit comprising the steps of:

providing an enhanced heat dissipating structure comprising a continuous electrically inactive conductor extending in one or more heat dissipating layers of a dielectric body dielectrically spaced from and along a heat dissipating substrate and

connecting said ~~an~~ electrically inactive conductor to said electrically active interconnect line as an ~~extensions~~ extension of said electrically active interconnect line to dissipate heat ~~therefrom~~ from said electrically active interconnect line through said enhanced heat dissipating layers of dielectric body.

2. (currently amended) The method of claim 1 wherein said electrically inactive conductor is on one or more ~~a heat dissipating layer~~ layers of ~~a~~ said dielectric ~~region~~ body forming one or more enhanced heat dissipating layers and these heat dissipating layers are closer to a heat dissipating substrate than said electrically active interconnect line.

3. (currently amended) The method of claim 2 wherein said electrically inactive conductor is connected to said electrically active interconnect line using one or more vias through said one or more ~~heat dissipating~~ layers of said dielectric body.

4. (currently amended) The method of claim3 wherein said electrically inactive conductor is connected to said electrically active interconnect line using at least two vias and a conducting pad through two or more ~~heat dissipating~~ layers of said dielectric body.

5. (currently amended) The method of Claim 2 wherein said dielectric ~~region~~ body includes dummy metal structures and said electrically inactive conductor is spaced from

and aligned with one or more of said dummy metal structures to aid in dissipating heat from said electrically inactive conductor.

6. (currently amended) The method of Claim 5 wherein said dummy metal structures is in said dielectric ~~region is~~ body between said electrically inactive conductor and said heat dissipating substrate.

7. (currently amended) The method of Claim 2 including the step of coupling said heat dissipating substrate to a heat sink.

8. (canceled)

9. (currently amended) The method of claim 1 wherein said electrically inactive conductor is in a straight line.

10. (original) The method of Claim 1 wherein said electrically inactive conductor is not in a straight line.

11. (original) The method of Claim 10 wherein said electrically inactive conductor is in the shape of an H with two parallel conductors and a cross connector connected to the electrically active connector.

12. (currently amended) The method of Claim 11 wherein in said connecting step said electrically inactive conductor is in ~~the~~ a heat dissipating dielectric layer of said dielectric body adjacent to said electrically active conductor ~~and closer to said substrate~~ and wherein said electrically inactive conductor and ~~the~~ a via connection to the electrically inactive conductor is formed by ~~the~~ a damascene process.

13. (currently amended) An integrated circuit, comprising:

an electrically active interconnect line within a dielectric ~~layer~~ body having a top and bottom surface, the bottom surface of the dielectric ~~layer~~ body being coupled to the top

surface of a heat dissipating substrate underlying the dielectric ~~layer~~ body; ~~said dielectric layer having horizontally arranged heat dissipating heat dissipating layers~~ and an electrically inactive continuous conductor within said dielectric ~~layer~~ body at one or more layers of said body ~~a heat dissipating layer~~ closer to the heat dissipating substrate than said active interconnect line with dielectric material separating the inactive conductor from said heat dissipating substrate; said electrically inactive conductor coupled to said electrically active interconnect line as an extensions of electrically active interconnect line to dissipate heat therefrom.

14. (currently amended) The integrated circuit of Claim 13 wherein said electrically inactive conductor is connected to said electrically active interconnect line using one or more vias through one or more ~~heat dissipating~~ layers of said dielectric body.

15. (currently amended) The integrated circuit of Claim 14 wherein said electrically inactive conductor is connected to said electrically active interconnect line using at least two vias and a conducting pad through two or more ~~heat dissipating~~ layers of said dielectric body .

16. (currently amended) The integrated circuit of Claim 14 wherein said dielectric ~~region~~ body includes dummy metal structures in one or more layers of said dielectric body and said electrically inactive conductor is aligned with and spaced from one or more of said dummy metal structures to aid in dissipating heat from said electrically inactive conductor.

17. (currently amended) The integrated circuit of Claim 16 wherein said dummy metal structures ~~is~~ in said dielectric ~~region~~ body is between said electrically inactive conductor and said substrate.

18. (original) The integrated circuit of Claim 13 including means for coupling said heat dissipating substrate to a heat sink.

19. (canceled)

20. (canceled)

21. (new) A method of dissipating heat in an electrically active interconnect line in an integrated circuit comprising the steps of:

providing a continuous electrically inactive conductor in a dielectric body with dielectric material separating the inactive conductor from a heat dissipating surface that is one of either a bottom silicon substrate connected by bonding to a package or a top surface of an integrated circuit chip connected by bonding to a package and connecting said electrically inactive conductor to said electrically active interconnect line to dissipate heat therefrom.

22. (new) The method of claim 21 wherein said electrically inactive conductor is on one or more metal layers embedded within said dielectric body.

23. (new) The method of claim 22 wherein some portions of said electrically inactive conductor are closer to said heat dissipating surface than said electrically active interconnect line, thereby improving its heat dissipating characteristics to said heat dissipating surface.

24. (new) The method of claim 22 wherein some portions of said electrically inactive conductor have larger spatial dimensions in a metallization layer than said electrically active line thereby improving its heat dissipating characteristics to a heat dissipating surface.